

Features:

- Modular & Fanless designed, aluminum-magnesium alloy;
- Intel 12th Gen. Alder Lake-U Core i3/i5/i7 processors;
- 19.0" TFT LCD Display, LED Backlit, SXGA 1280*1024;
- Multi up to 10 points Pcap. touchscreen, EETI controller;
- DC terminal, wide 9~36 V input range;
- 2 RJ45, 2 USB3.1, 2 USB3.0, 3 COM, 1 HDMI, 1 DP, Audio;
- 1 USB type-C (USB3.1 & DP1.4a), 1 SW Remote Switch;
- Intel PTT TPM2.0, Support Windows 11 OS;
- Panel mount, VESA 75/100 mount, Front IP65 rated protection;
- Optional 2 M.2 and 1 Mini-PCle expansion slots.

Specification



Hardware & System

BIOS	SPI AMI EEL BIOS
CPU	Intel 12 th Gen. Core i3-1215U, Core i5-1235U, Core i7-1255U
Graphic	Intel UHD/Iris Xe Graphic
Memory	2* SO-DIMM, Support DDR5-4800 MHz, Max. up to 64GB
Storage	1* M.2 2280 M-Key slot (PCIe x4 Gen IV, NVMe) SSD, 1* M.2 2280 M-Key slot (SATA) SSD ^[1] , 1* SATA3.0 SSD
Network	1* Intel I226 (2.5GbE), 1* Intel I219 (GbE) Network chips, optional 3G/4G/5G/Wi-Fi/BT, Wi-Fi6 wireless
Audio	On-board Realtek ACL 897 Audio controller
Expansion	1* M.2 (NGFF) B-Key 3042/3052 slot, 1* M.2 E-Key 2240 slot, 1* Mini-PCle slot, 1* SIM Card slot
Watch dog	0 ~ 256 seconds programmable
Operating System	Win10 IoT 2021 LTSC; Win10 (21H2), Win11(21H2 or later); Linux Kernel 5.17 or later

I/O Interface

Ethernet	2 RJ45
COM	COM1/2: RS232/RS485/RS422 (BIOS configured); COM3: RS232/GPIO
Audio	Mic-in/Line-out (2 in 1, 3.5mm Jack)
USB	2* USB3.1 (USB3.2 Gen2 x1, 10 Gbps), 2* USB3.0 (USB3.2 Gen1 x1, 5Gbps), 1* USB-C (USB3.1 & DP1.4a)
Display	1* HDMI1.4 (Max. resolution to 4K@30Hz), 1* DP++ (Max. support 8K @30Hz)
Power	1* 2 Pins, Phenix Terminal

LCD Display

Size/Type	19.0" TFT LCD Display
Resolution	1280 * 1024 (SXGA)
Brightness	250 nits
Backlit & Lifetime	LED Backlit & 30K hours
Display Area	376.32 * 301.06 (mm)
View Angle	85/85/80/80

Touchscreen

Type	Projective capacitive touchscreen
Touch points	Multi points touch, max. up to 10 points
Durability	>100 000 000 times
Surface Hardness	MOHS 6H
Touch Controller	EETI
Special Treatment	Anti-Fingerprint (AF)

Structure

Structure & Surface	Magnesium-Aluminum alloy, sand blasting, anodized treated
Cooling System	Large area finned heatsink (Fanless designed)
Overall Dimension	422.3 * 353.0 * 59.0 (mm)
Cut-out Dimension	411 * 342 (mm)
Net Weight	6.2 KG
Mount Method	Panel mount, VESA 75/100 Mount
Operating temp.	0 ~ + 50 (°C)

TPC-DCT190D

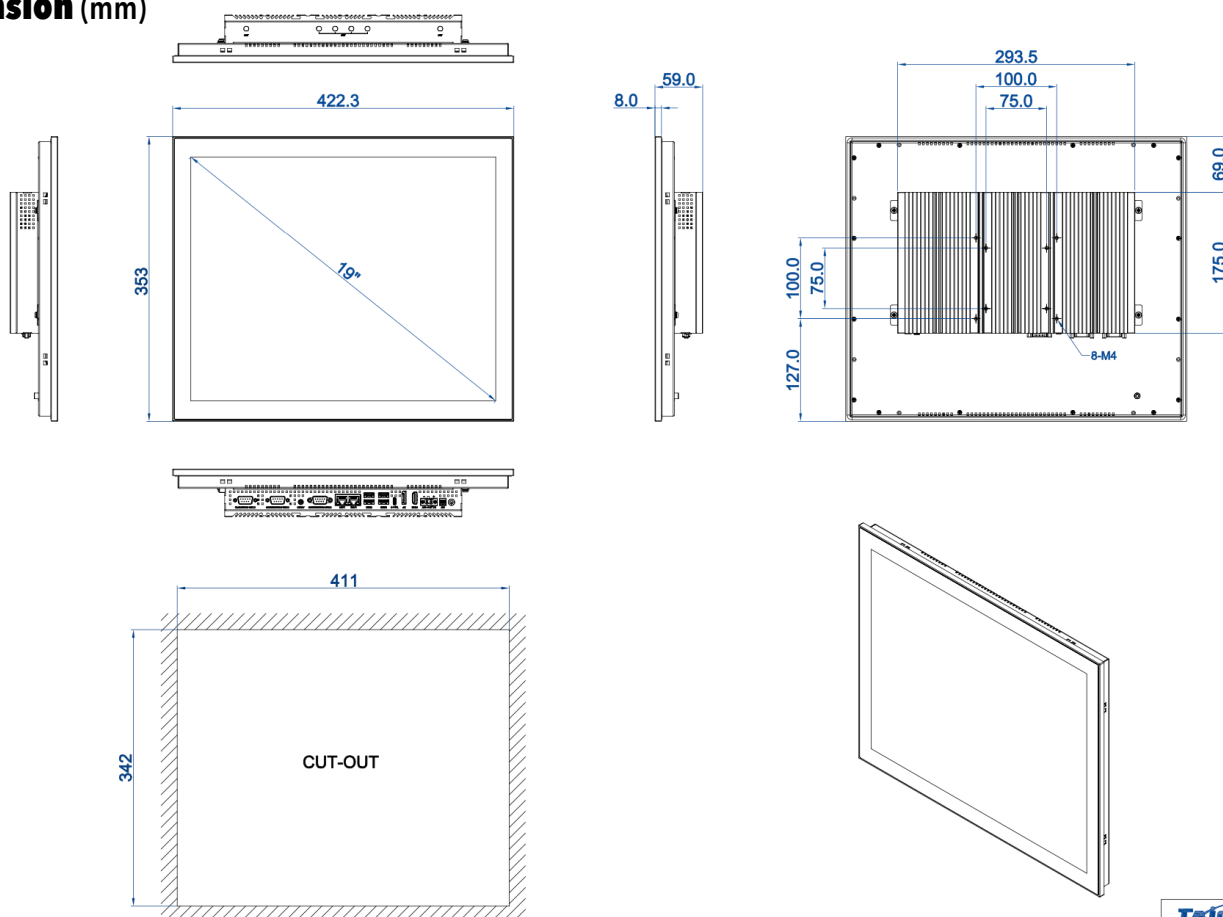
Power & Environmental

Storage temp.	-20 ~ + 60 (°C)
Humidity	10 ~ 95% @ 10C (No condensation)
Vibration	50 ~ 500 Hz, 1.5G, 0.15mm peak to peak
Shock	10G/Peak (11 ms)
Power input	Wide DC 9~36 V
Power consumption	About 40W
Certificate	CE/FCC/ROHS

[1] This M.2 slot Default as SATA SSD, optional as NVMe 4x SSD to support RAID 0/1 (selected by resistors).

DIMENSIONAL DRAWING:TPC-DCT190D

Dimension (mm)



DIMENSIONS IN MILLIMETERS

TAICEN
DATE:2024.10.22
REV:C Unit:mm

Ordering information

Part no.	Description	Packing List
TPC-DCT190D1	19.0" LCD, SXGA 1280 *1024, Intel Core i3-1215U, Pcap.Touch, 2 RJ45, 2 USB3.1, 2 USB3.0, 1 USB-C, 1 HDMI, 1 DP, 3 COM, Audio, 1 SW, DC 9~36V, PSU	
TPC-DCT190D2	19.0" LCD, SXGA 1280 *1024, Intel Core i5-1235U, Pcap.Touch, 2 RJ45, 2 USB3.1, 2 USB3.0, 1 USB-C, 1 HDMI, 1 DP, 3 COM, Audio, 1 SW, DC 9~36V, PSU	
TPC-DCT190D3	19.0" LCD, SXGA 1280 *1024, Intel Core i7-1255U, Pcap.Touch, 2 RJ45, 2 USB3.1, 2 USB3.0, 1 USB-C, 1 HDMI, 1 DP, 3 COM, Audio, 1 SW, DC 9~36V, PSU	
Optional Accessories	Description	Packing List
Memory	SO-DIMM, DDR5, 8GB/16GB/32GB/64GB	Standard TPC-DCT190D Panel PC Product 1 set
Storage	SSD: 128GB/256GB/512GB/1TB/2TB	PSU (90W Power Supply) 1 set
Wireless	Wi-Fi Module, with Antenna	Panel mount clips (Metal) 1 set (8 pieces)
	Wi-Fi Module with BT Integrated, With Antenna	Power Cable & Plug 1 set
	All Network 4G module, with Antenna	
	5G Network module, with Antenna	

The information in this specification is subject to change without notice.